

GBU



Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
260°C/10 seconds at terminals

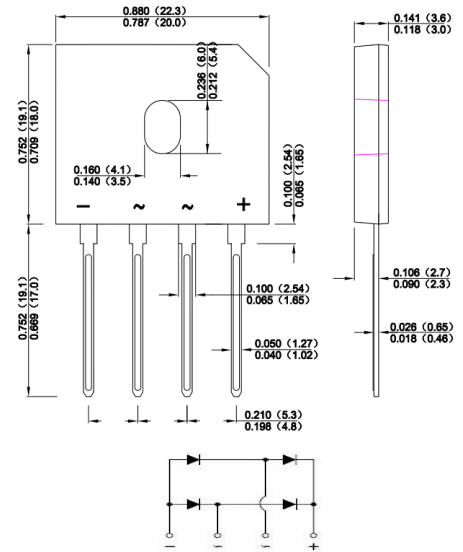
Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	GBU 12005	GBU 1201	GBU 1202	GBU 1204	GBU 1206	GBU 1208	GBU 1210	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	12.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	240.0							A
Rating for fusing ($t=8.3ms$, $T_A=25^\circ C$)	I_t^2	239							A^2s
Maximum instantaneous forward voltage at 12.0A	V_F	1.10							V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=125^\circ C$	I_R	2.0 200							μA
Typical junction capacitance (Note 1)	C_J	58.0							pF
Typical thermal resistance	R_{qJA}	25.0							$^\circ C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ C$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

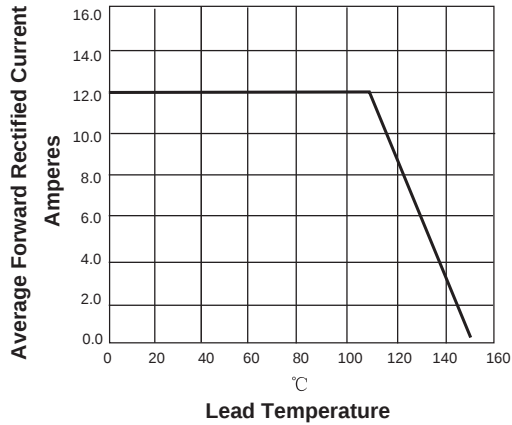


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

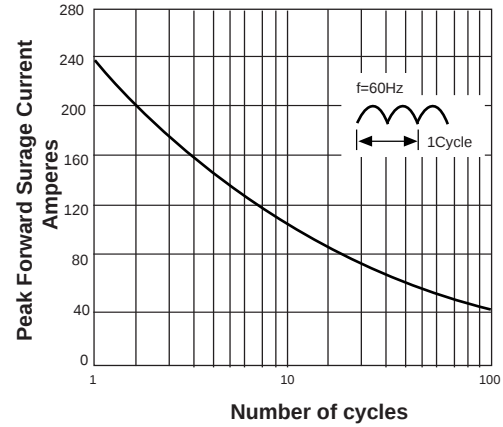


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

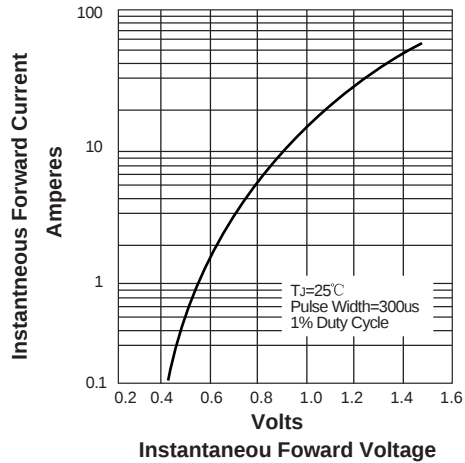
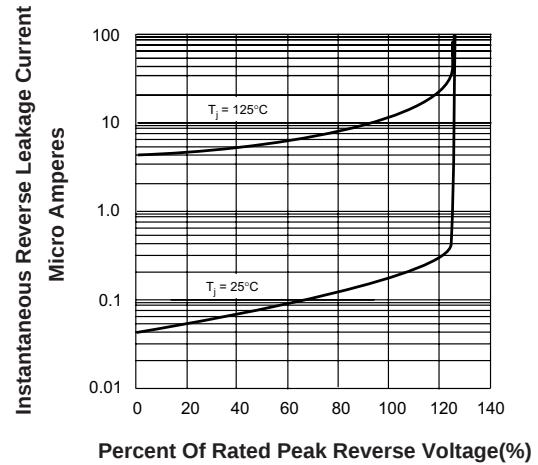
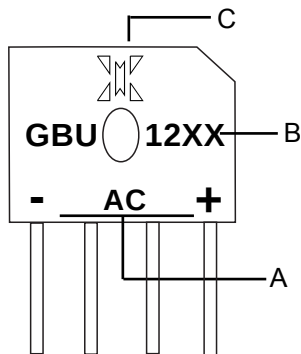


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

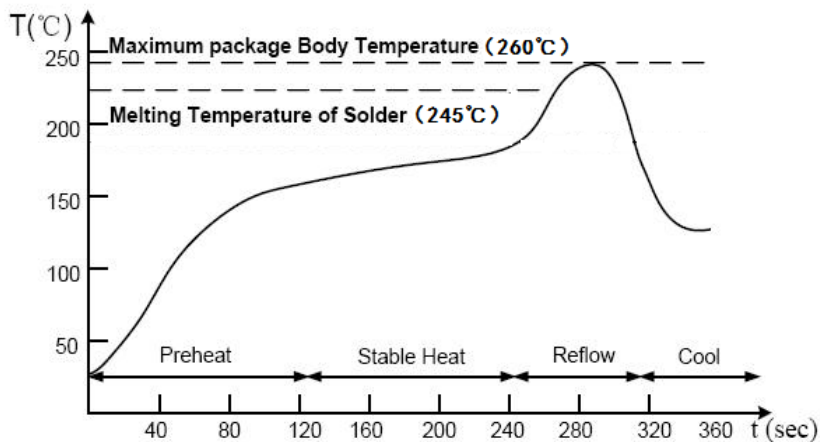


Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name, X : 005.01.....10
C	Logo

Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
GBU	478*41.4*6.5	0.02	495*130*70	0.6	510*375*165	3

Bulk Package

Package	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
GBU	252*202*40	0.5	460*245*165	3